

### Product Features

- Superior thermal conductivity
- Excellent electrical properties
- UL-94 V-0 equivalent flame rating
- Superior reworkability

### Typical Applications

- Electronics applications requiring thermal dissipation

### Typical Properties

Type	Liquid-dispensed Gap Filling Rubber
Cure Type	Addition
One/Two Component	Two
Low Molecular Weight Siloxane Stripped?	Y
Color	Gray
Density @ 23C (g/cm <sup>3</sup> )	3.08
Viscosity (Pa·s)	89
Mix Ratio by Weight	100:100
Cure Conditions	24hr @ 25C
Tack Free Time (min)	360
Working Time	4 Hours
Shore 00 Hardness	44
Tensile Strength (MPa)	0.10
% Elongation	40
Volume Resistivity (TΩ·m)	1.800
Dielectric Strength (kV/mm)	20.0
Dielectric Dissipation Factor	4 x 10 <sup>-3</sup> @ 50Hz
Dielectric Constant	6.0 @ 50Hz
Thermal Conductivity (W/m·K)	3.50
Thermal Resistance (mm <sup>2</sup> ·K/W)	37
Usable Temp. Range (C)	-40 to +180
Bond Line Thickness (µm)	120

*Note: Values are not for specification purposes.*

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